PFC Device Corporation

Wafer MSDS

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MATERIAL SAFETY DATA SHEET

1. IDENTIFICATION

Product Name : 6" Integrated Circuit

Product Code : General Use : Product Description :

MANUFACTURE

Company Name : PFC Device Corporation Taiwan Branch

Address : 3F., No.82, Min-Chuan Rd., Hsin-Ten Dist., New Taipei City 23141,

Taiwan, R.O.C.

Responsible Div

Telephone : (02) 2218-1555 Fax : (02) 2218-9160

EMERGENCY TELEPHONE NUMBER: (02) 2218-1555

2. COMPOSITION/INFORMATION ON INGREDIENTS

Substance/Mixture : Mixture

Composition(element)	CAS No.	Proportion
Silicon (Si)	7440-21-3	96.5%
Other minority Dopant :		
Silver (Ag)	7440-22-4	1.7%
Aluminum (AI)	7429-90-5	1.2%
Nickel (Ni)	7440-02-0	0.3%
Titanium (Ti)	7440-32-6	0.1%
Arsenic (As)	7440-38-2	0.1%
Impure(Boron/Phosphorous/Copper)		0.1%

3. HAZARDS INDENTIFICATION

Hazard effects

Human health effects : Skin contact causes irritation.

Environmental effects : NA Class name of hazard : NA

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4. FIRST AID MEASURES

Inhalation : NA Eye : NA

5. FIRE FIGHTING MEASURES

Measures : Shut off fuel as much as possible.

Equipments : Dry chemical or carbon dioxide should be used for small fire.

: Fire fighters should wear proper protective clothes.

6. ACCIDENTAL RELEASE MEASURES

: Equip extinguishers in case of ignition. : Quickly shut off all ignition sources.

7. HANDLING AND STORAGE

Handling : Fragile-Handle with care.

: Shut off all sources of ignition.

: Do not bring contaminated protective tool, such as gloves, to

the lounge.

: Be careful of personal health after handling.

Storage : Keep away all sources of ignition.

: Do not heat.

: Store in well-ventilated area.

: Keep dry.

8. EXPOSURE CONTRROLS/PERSONAL PROTECTION

EXPOSURE LIMIT VALUES : NA

EXPOSURE CONTROLS

Engineering controls : NA

Personal protection

Respiratory protection : NA Eye protection : NA Skin protection : NA **PFC Device Corporation**

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9. PHYSICAL AND CHEMICAL PROPERTIES

Appearance : Chip Color : Silver

Boiling Point : Not Available

Melting Point : Density : Vapor Pressure : Vapor Density : -

Solubility in water : Insoluble

10. STABILTY AND REACTIVITY

STABILITY : Stability

MATERIALS TO AVOID : -

11. TOXICOLOGICAL INFORMATION

Acute toxicity
Sensitization Chronic Toxicity Mutagen city Carcinogenicity IARC NTP OSHA Reproductive and
Developmental Toxicity
Other -

12. ECOLOGICAL INFORMATION

ECOTOXICITY PERSISTECE AND
DEGRADABILITY
BIOACCUMULATIVE

POTENTIAL

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13. DISPOSAL CONSIDERATION

Disposal method :All excess material must be collected and transferred to a

professional waste disposal company for treatment.

:Carefully review information in -7.HANDLING & STORAGE.

Special control industrial

disposal

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14. TRANSPORT INFORMATION

UN sorts -

Domestic regulation

Special safety measurement

and condition

15. REGULATIORY INFORMATION

NA

16. OTHER INFORMATION

NA